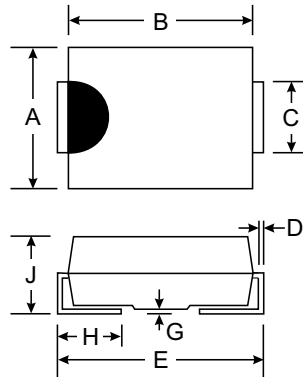


### Features

- Guard Ring Die Construction for Transient Protection
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application
- Plastic Material - UL Flammability Classification 94V-0



Dim	SMA		SMB	
	Min	Max	Min	Max
A	2.29	2.92	3.30	3.94
B	4.00	4.60	4.06	4.57
C	1.27	1.63	1.96	2.21
D	0.15	0.31	0.15	0.31
E	4.80	5.59	5.00	5.59
G	0.10	0.20	0.10	0.20
H	0.76	1.52	0.76	1.52
J	2.01	2.62	2.00	2.62

All Dimensions in mm

### Mechanical Data

- Case: Molded Plastic
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Approx. Weight: SMA 0.064 grams  
SMB 0.093 grams
- Marking: Type Number

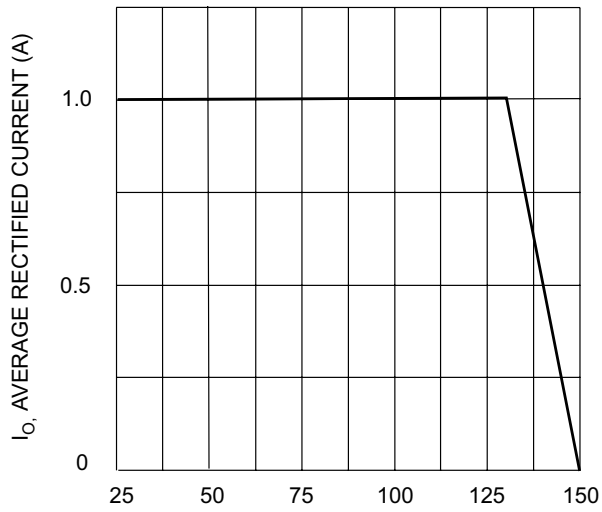
No Suffix Designates SMA Package  
"B" Suffix Designates SMB Package

### Maximum Ratings and Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

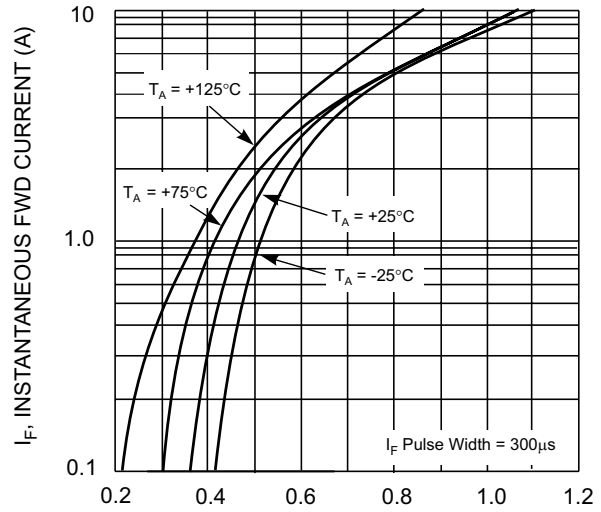
Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	B120/B	B130/B	B140/B	B150/B	B160/B	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	20	30	40	50	60	V
Working Peak Reverse Voltage	V <sub>RWM</sub>						
DC Blocking Voltage	V <sub>R</sub>						
RMS Reverse Voltage	V <sub>R(RMS)</sub>	14	21	28	35	42	V
Average Rectified Output Current @ T <sub>T</sub> = 130°C	I <sub>O</sub>	1.0					A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30					A
Forward Voltage @ I <sub>F</sub> = 1.0A	V <sub>FM</sub>	0.50		0.70			V
Peak Reverse Current at Rated DC Blocking Voltage @ T <sub>A</sub> = 25°C @ T <sub>A</sub> = 100°C	I <sub>RM</sub>	0.5			10		mA
Typical Junction Capacitance (Note 2)	C <sub>J</sub>	110					pF
Typical Thermal Resistance Junction to Terminal (Note 1)	R <sub>θJT</sub>	20					°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150					°C

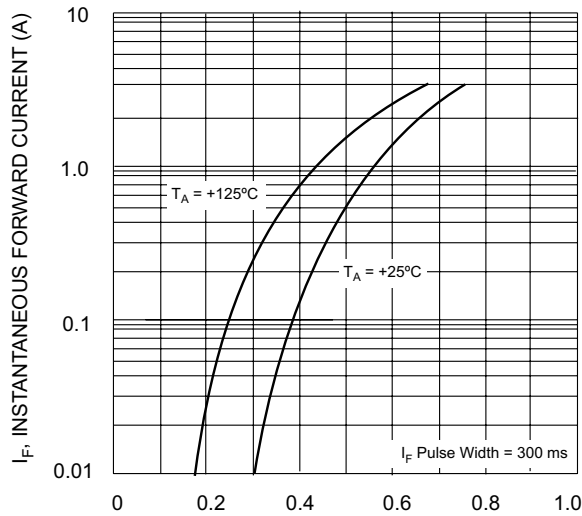
Notes: 1. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm<sup>2</sup> (0.013 mm thick) copper pads as heat sink.  
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.



$T_T$ , TERMINAL TEMPERATURE (°C)  
Fig. 1 Forward Current Derating Curve



$V_F$ , INSTANTANEOUS FORWARD VOLTAGE (V)  
Fig. 2 Typical Forward Characteristics - B120/B thru B140/B



$V_F$ , INSTANTANEOUS FWD VOLTAGE (V)  
Fig. 3 Typ. Forward Characteristics - B150/B thru B160/B

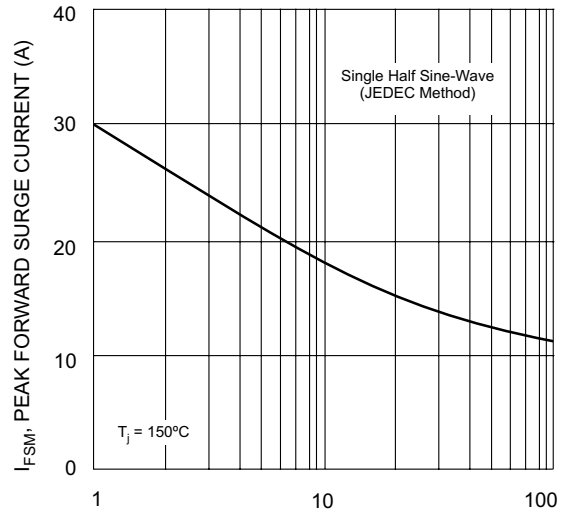
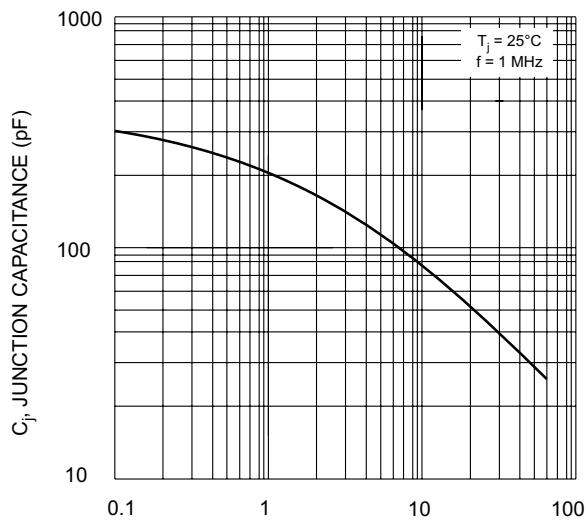
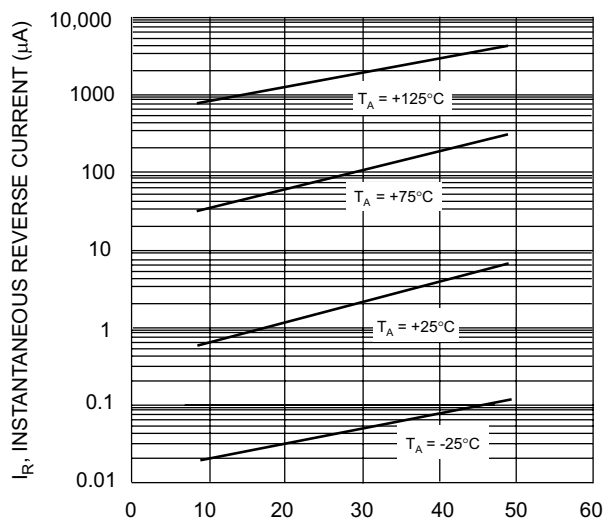


Fig. 4 Max Non-Repetitive Peak Fwd Surge Current



$V_R$ , REVERSE VOLTAGE (V)  
Fig. 5 Typical Junction Capacitance



$V_R$ , INSTANTANEOUS REVERSE VOLTAGE (V)  
Fig. 6 Typical Reverse Characteristics, B120/B thru B140/B

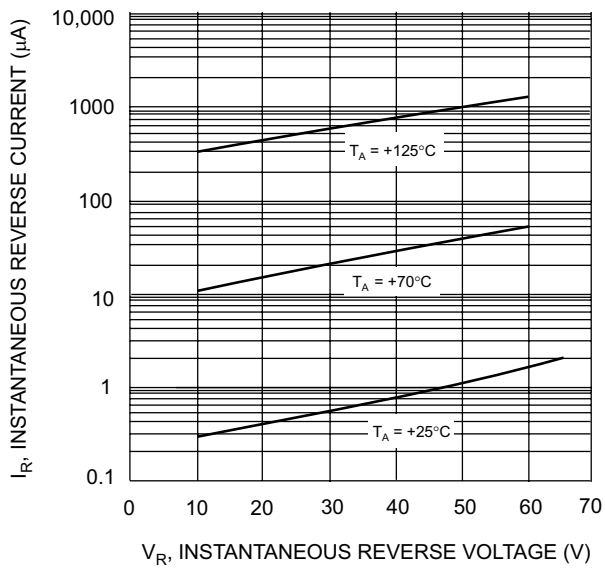


Fig. 7 Typical Reverse Characteristics, B150/B thru B160/B